

SOT1049-1

plastic extremely thin quad flat pack package; no leads; 10 terminals; UTLP based

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN10U
Package type industry code	XQFN10U
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package style suffix code	U (UTLP based)
Package body material type	P (plastic)
IEC package outline code	- - -
JEDEC package outline code	MO-255
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	5-2-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.45	-	1.55	1.65	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.58	-	mm
n ₂	actual quantity of termination	-	-	10	-	

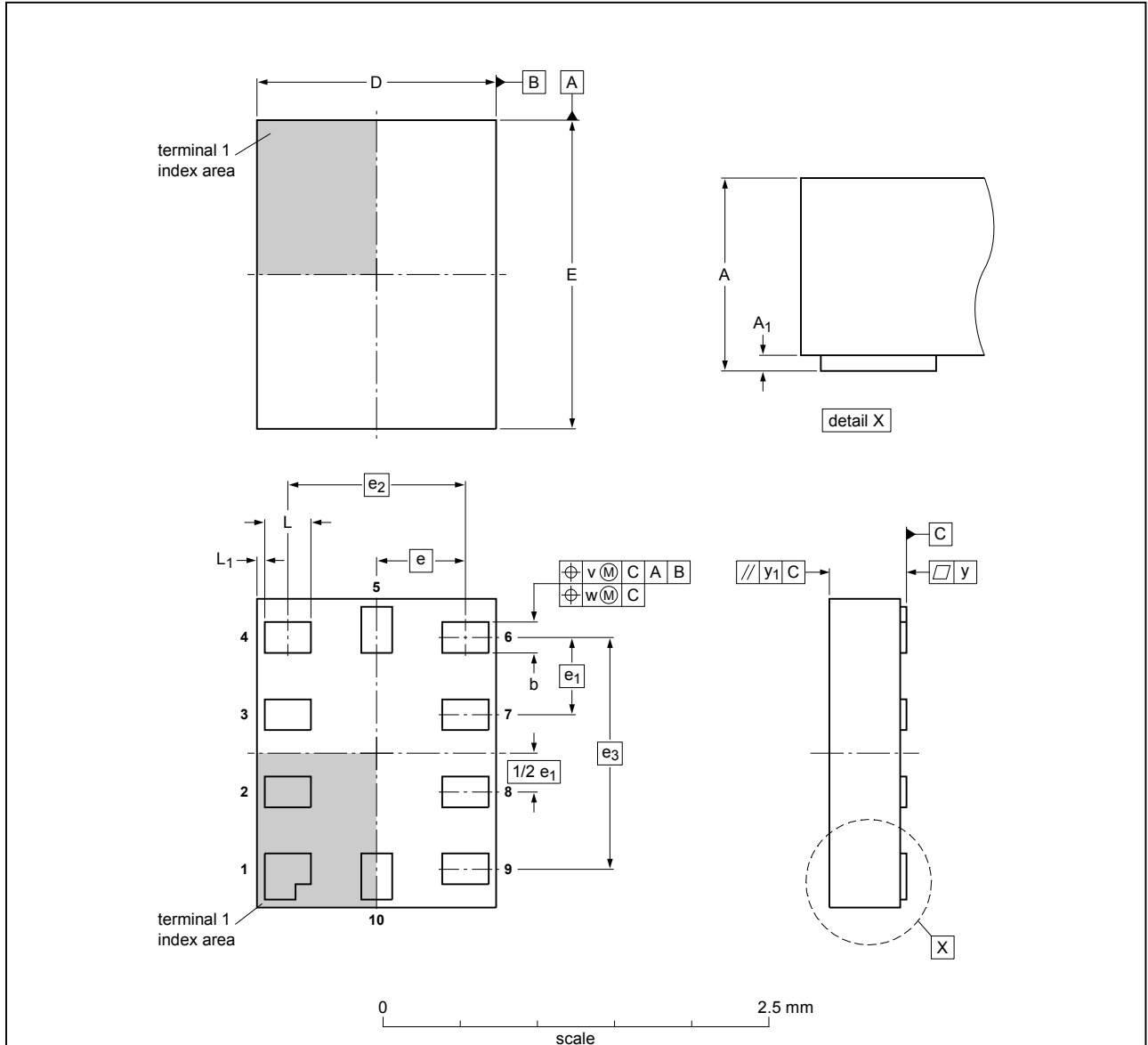


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2. Package outline

XQFN10U: plastic extremely thin quad flat pack package; no leads; 10 terminals; UTLP based; body 2 x 1.55 x 0.5 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	D	E	e	e ₁	e ₂	e ₃	L	L ₁	v	w	y	y ₁	
mm	max	0.50	0.05	0.30	1.65	2.1	0.58	0.5	1.16	1.5	0.4	0.15	0.3	0.08	0.1	0.05
	nom		0.03	0.23	1.55	2.0					0.3					
	min		0.00	0.15	1.45	1.9					0.2					

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1049-1	---	MO-255	---			08-02-28 10-02-05

Fig. 1. Package outline XQFN10U (SOT1049-1)

3. Soldering

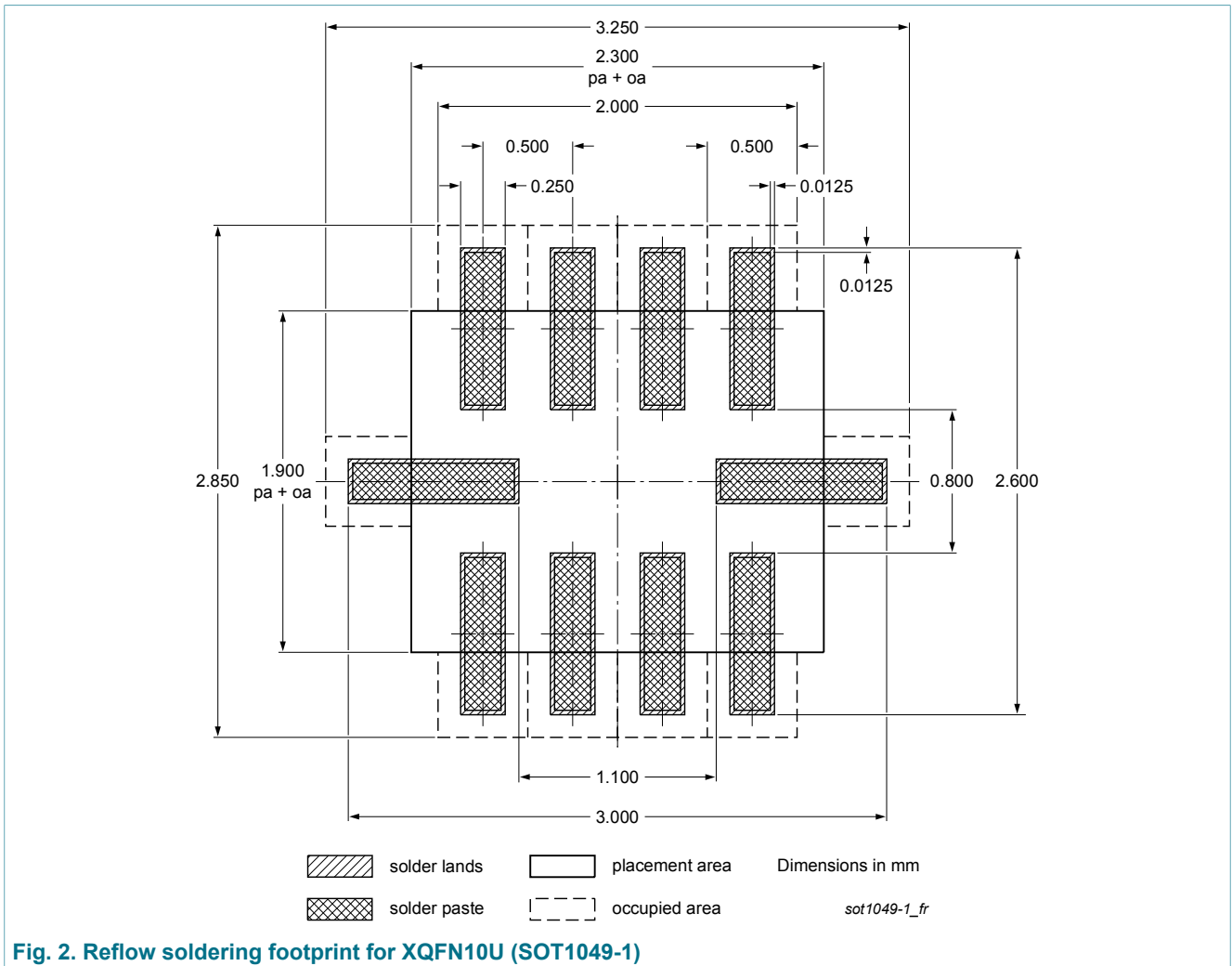


Fig. 2. Reflow soldering footprint for XQFN10U (SOT1049-1)

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4. Legal information

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